

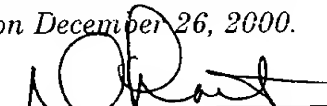
2826

PATENT #5/Electr  
1-10-00  
2/Dirde

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



I hereby certify that this correspondence is being deposited with the U.S. Postal Service as first class mail in an envelope addressed to Commissioner of Patents and Trademarks, Washington, D.C. 20231 on December 26, 2000.

  
Debbie Prout

Applicant : Rong-Fuh Shyu  
Application No. : 09/383,150  
Filed : August 25, 1999  
Title : LEAD FRAME FOR A  
SEMICONDUCTOR CHIP PACKAGE,  
SEMI CONDUCTOR CHIP PACKAGE  
INCORPORATING MULTIPLE  
INTEGRATED CIRCUIT CHIPS,  
AND METHOD OF  
FABRICATING...  
Grp./Div. : 2826  
Examiner : F. Abraham  
Docket No. : 35761/DBP/S295

RECEIVED  
JAN - 8 2001  
TECHNOLOGY CENTER 2800

RESPONSE RE ELECTION OF CLAIM GROUP

Assistant Commissioner for Patents  
Washington, D.C. 20231  
Post Office Box 7068  
Pasadena, CA 91109-7068  
December 26, 2000

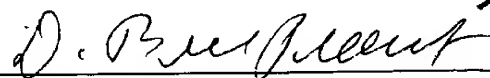
Commissioner:

This is in response to the Official office action dated November 30, 2000.

Applicant hereby elects Claim Group I, claims 1-8, drawn to a packaging of a device.

Respectfully submitted,

CHRISTIE, PARKER & HALE, LLP

By   
D. Bruce Prout  
Reg. No. 20,958  
626/795-9900

DBP/djp  
DJP PAS293561.1--12/26/00 1:08 PM